

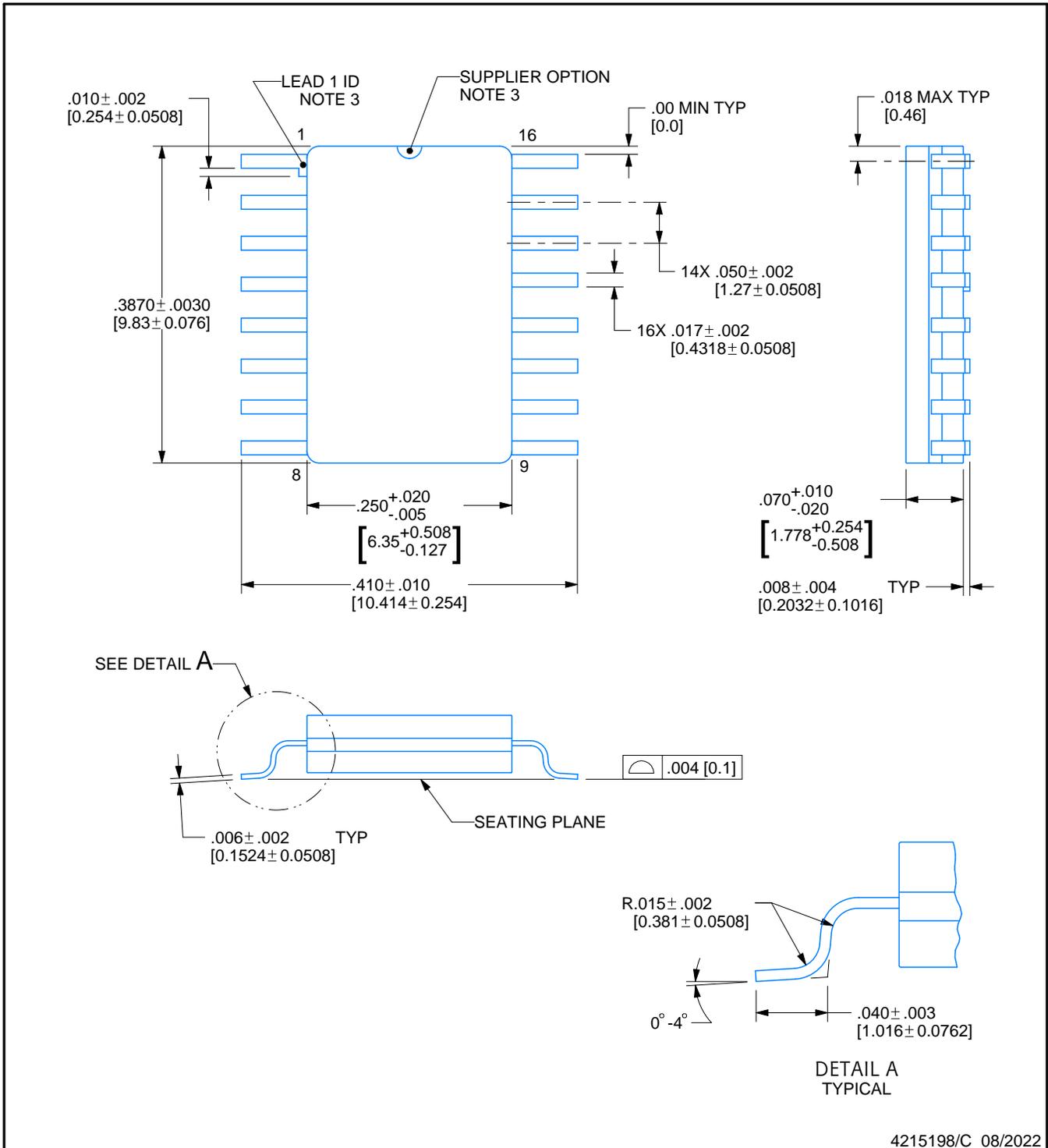


# PACKAGE OUTLINE

## NAC0016A

### CFP - 2.33mm max height

CERAMIC FLATPACK



4215198/C 08/2022

#### NOTES:

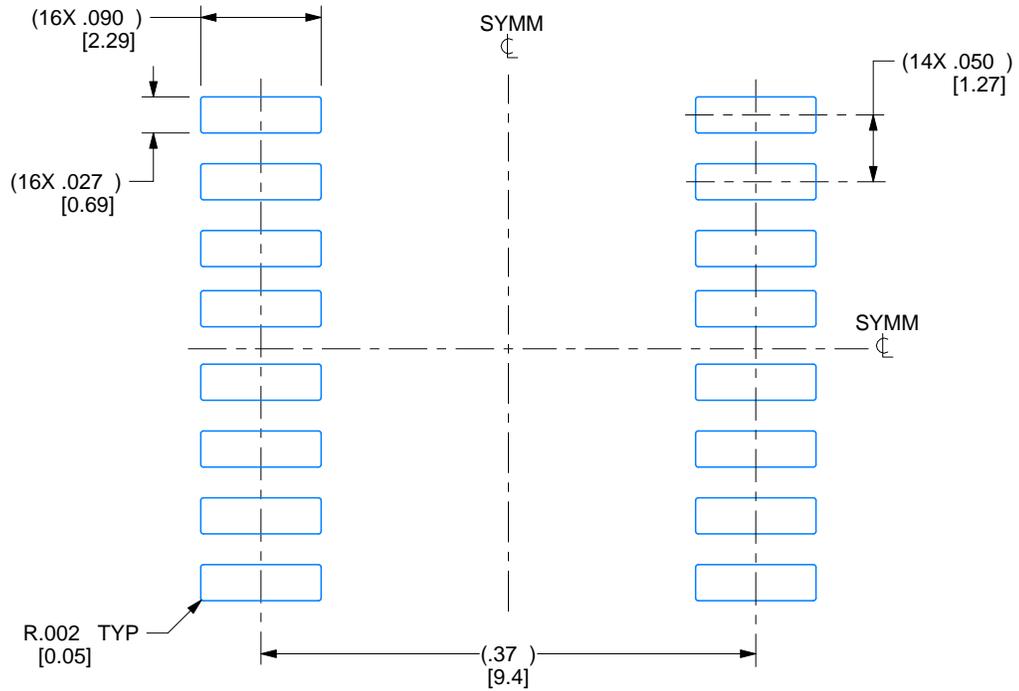
- Controlling dimension is Inch. Values in [ ] are millimeters. Dimensions in ( ) for reference only.
- For solder thickness and composition, see the "Lead Finish Composition/Thickness" link in the packaging section of the Texas Instruments website
- Lead 1 identification shall be:
  - A notch or other mark within this area
  - A tab on lead 1, either side
- No JEDEC registration as of December 2021

# EXAMPLE BOARD LAYOUT

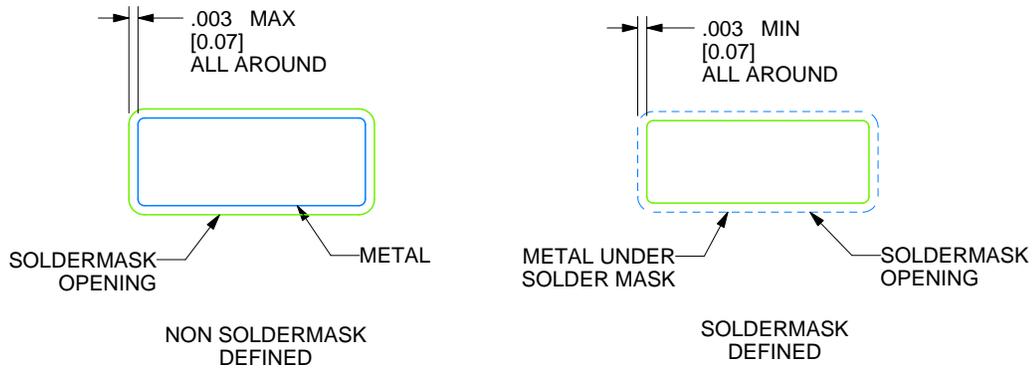
NAC0016A

CFP - 2.33mm max height

CERAMIC FLATPACK



RECOMMENDED LAND PATTERN



4215198/C 08/2022

## REVISIONS

REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2197879	12/30/2021	TINA TRAN / ANIS FAUZI
B	NO CHANGE TO DRAWING; REVISION FOR YODA RELEASE;	2198832	02/15/2022	K. SINCERBOX
C	.387±.003 WAS .39000±.00012;	2200917	08/08/2022	D. CHIN / K. SINCERBOX

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